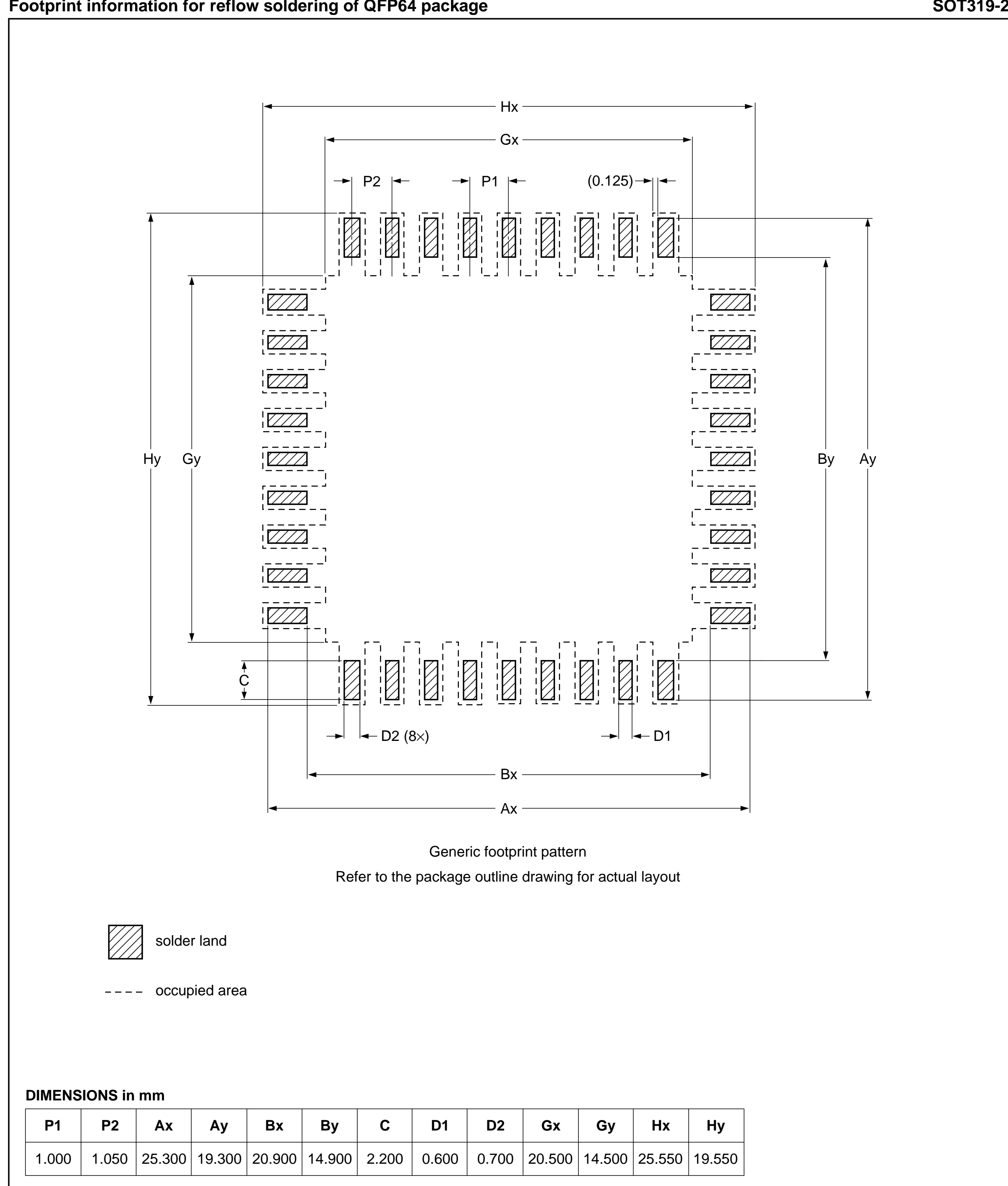
Footprint information for reflow soldering of QFP64 package **SOT319-2**



Generic footprint pattern

Refer to the package outline drawing for actual layout

DIMENSIONS in mm

P1	P2	Ax	Ay	Bx	By	C	D1	D2	Gx	Gy	Hx	Hy
1.000	1.050	25.300	19.300	20.900	14.900	2.200	0.600	0.700	20.500	14.500	25.550	19.550

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